

What is claimed is:

1. An anisotropic-electroconductive adhesive comprising:
an insulating adhesive component containing a radical polymerizable compound
5 and a polymerization initiator; and
a plurality of insulating coated electroconductive particles dispersed in the
insulating adhesive component, the insulating coated electroconductive particle having a
coating layer made of insulating thermoplastic resin on a surface of an electroconductive
particle,
10 wherein a softening point of the insulating thermoplastic resin is lower than an
exothermic peak temperature of the insulating adhesive component.
2. An anisotropic-electroconductive adhesive according to claim 1,
wherein the exothermic peak temperature of the insulating adhesive component
15 is in the range of 80°C ~ 120°C.
3. An anisotropic-electroconductive adhesive according to claim 1,
wherein the coating layer made of the insulating thermoplastic resin has a
thickness of 0.01 μ m ~ 10 μ m.
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4. An anisotropic-electroconductive adhesive according to claim 1 or 3,
wherein the electroconductive particle is made by forming a metal thin layer
onto a surface of a nucleus material.
- 25 5. An anisotropic-electroconductive adhesive according to claim 1 or 2,

wherein the insulating adhesive component further includes thermosetting resin and a curing agent.

6. An anisotropic-electroconductive adhesive according to claim 1,
5 wherein the radical polymerizable compound is acrylate based or metacrylate based compound.

7. An anisotropic-electroconductive adhesive according to claim 1 or 2,
10 wherein the polymerization initiator is organic peroxide.

8. An anisotropic-electroconductive adhesive according to claim 1 or 2,
wherein the insulating adhesive component further includes thermoplastic resin.

9. A circuit connection method comprising the steps of:

15 (a) interposing an anisotropic-electroconductive adhesive including an insulating adhesive component containing a radical polymerizable compound and a polymerization initiator; and a plurality of insulating coated electroconductive particles dispersed in the insulating adhesive component, the insulating coated electroconductive particle having a coating layer made of insulating thermoplastic resin on a surface of an electroconductive
20 particle, wherein a softening point of the insulating thermoplastic resin is lower than an exothermic peak temperature of the insulating adhesive component, between circuit boards respectively having circuit electrodes faced each other;

(b) electrically connecting the faced circuit electrodes by removing a part of the insulating thermoplastic resin coating layer on the surface of the electroconductive
25 particle contacted with the faced circuit electrodes by means of thermal pressing; and

(c) curing the insulating adhesive component so that the circuit electrodes are adhered and fixed.

10. A circuit connection structure in which the anisotropic-electroconductive
5 adhesive defined in the claim 1 is interposed between circuit boards respectively having circuit electrodes faced each other so that the circuit electrodes are electrically connected each other.